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United States Patent [19]

Takagi et al.

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- [54] SEMICONDUCTOR PACKAGE
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- [73] Assignee: **Sony Corporation**, Tokyo, Japan
- [**] Term: **14 Years**
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- [51] LOC (6) Cl. **13-03**
- [52] U.S. Cl. **D13/182**
- [58] Field of Search D13/182; 174/52.2-52.4; 206/710-719; 257/254, 659, 666, 678-697, 709, 730, 738, 780, 796; 437/183, 217, 220; 361/730

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[57] CLAIM

The ornamental design for a semiconductor package, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of a semiconductor package showing our new design; FIG. 2 is a top plan view thereof; FIG. 3 is a left side elevational view thereof; FIG. 4 is a front elevational view thereof; FIG. 5 is a bottom plan view thereof; FIG. 6 is a right side elevational view thereof; FIG. 7 is a rear elevational view thereof; FIG. 8 is a perspective view of another embodiment of a semiconductor package showing our new design; and, FIG. 9 is a front elevational view of the embodiment of FIG. 8. The rest of views of the embodiment of FIG. 8 are the same as those of the embodiment of FIG. 1.

[56] References Cited

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1 Claim, 4 Drawing Sheets

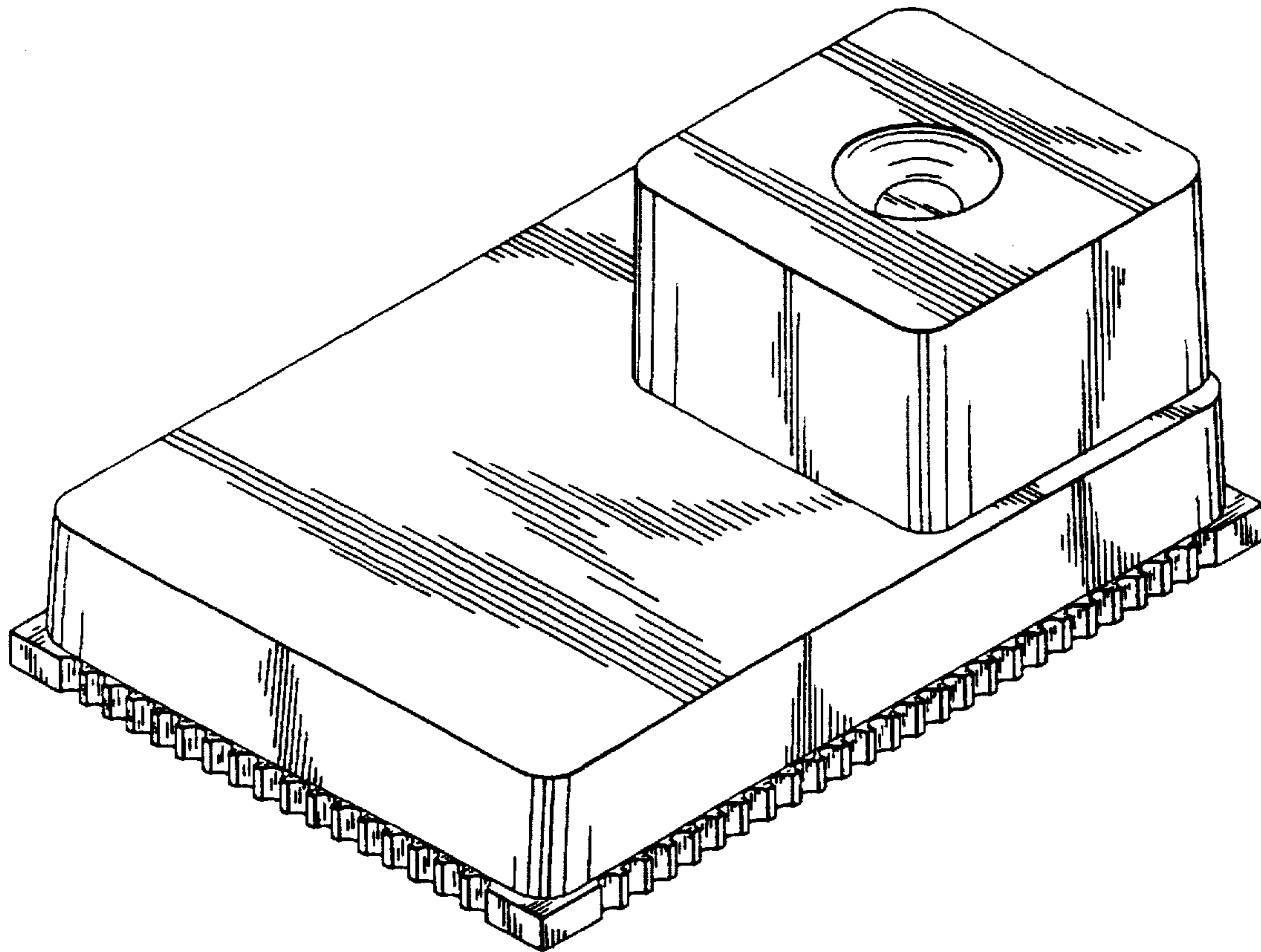


FIG. 1

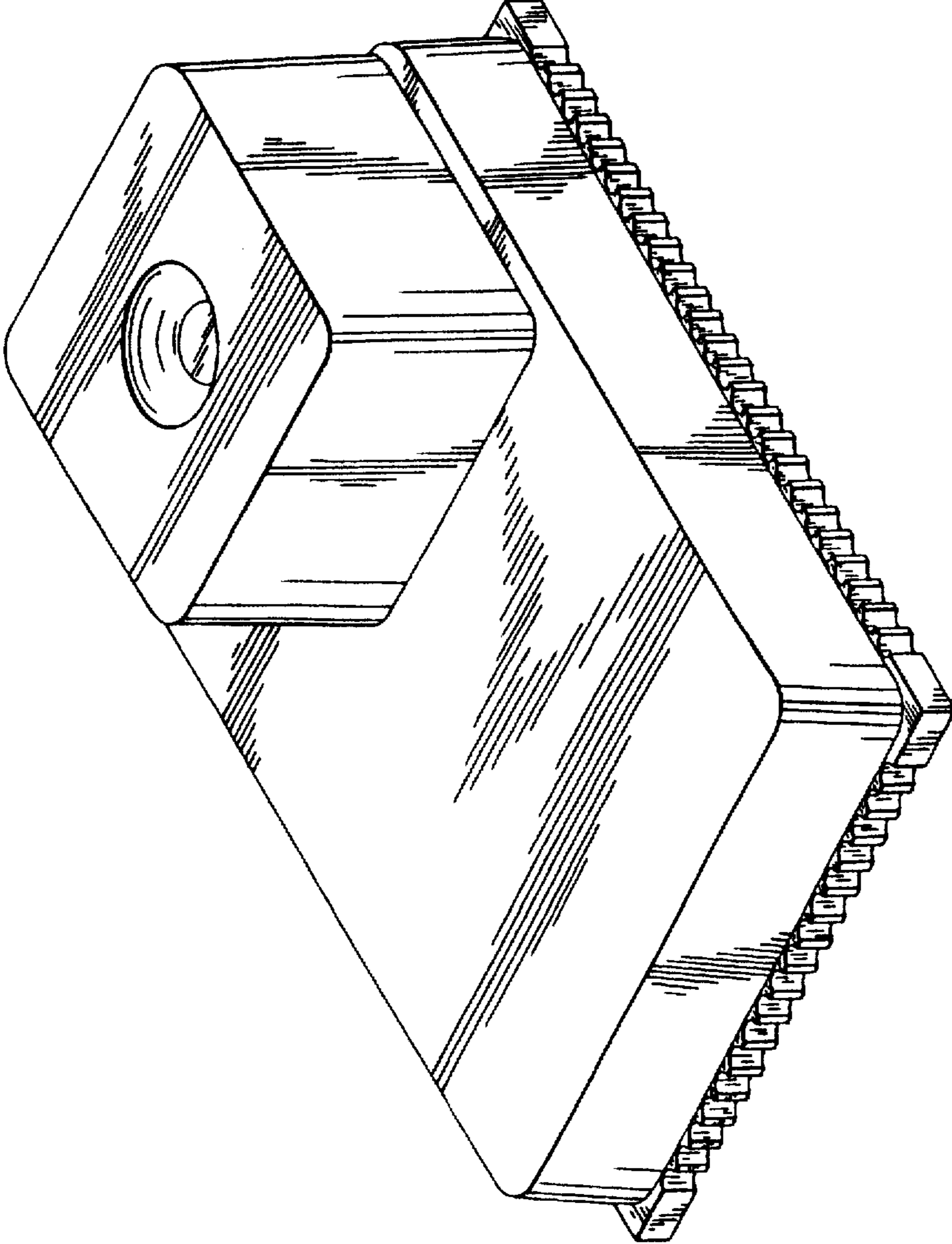


FIG. 2

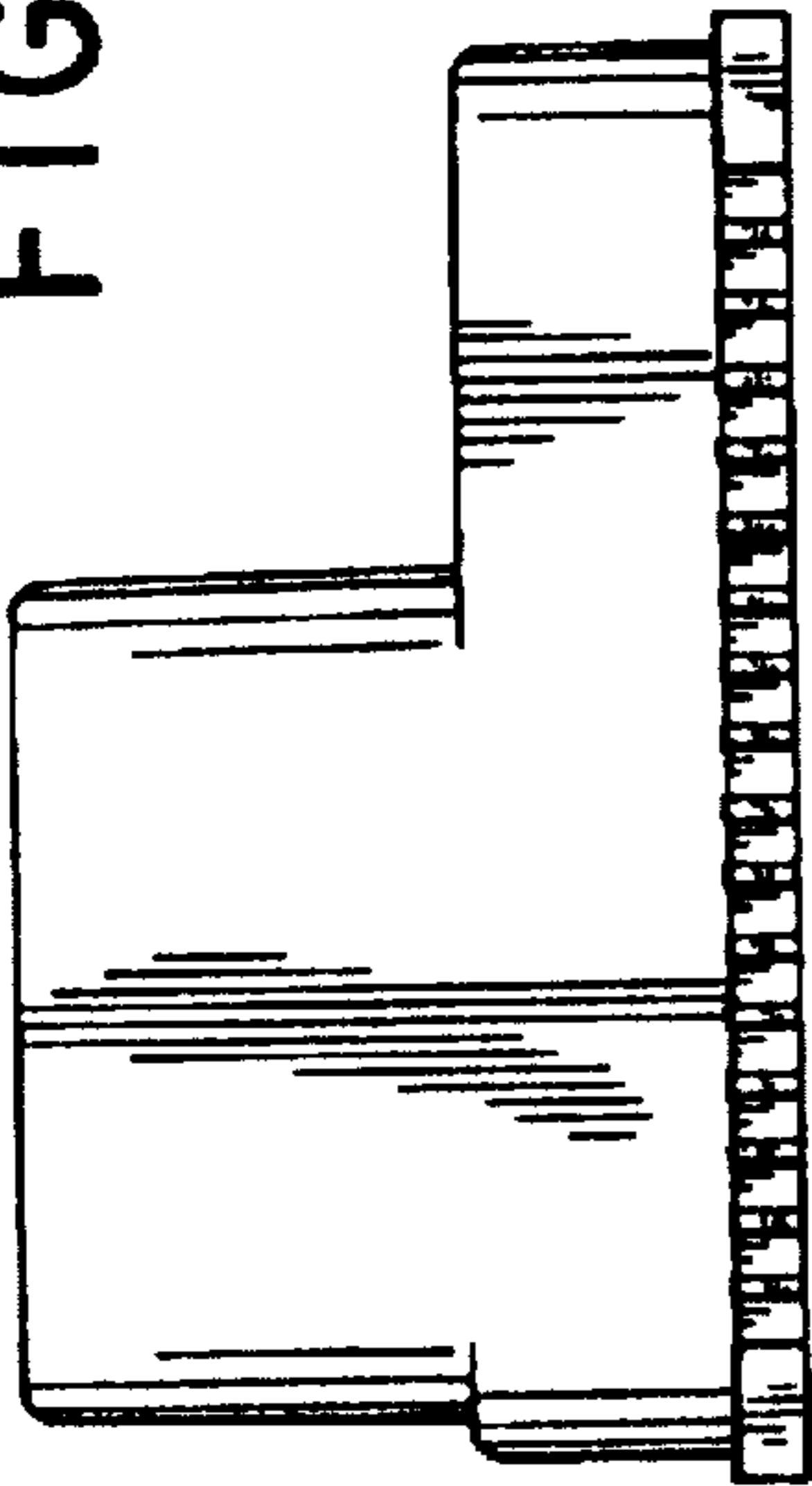


FIG. 3



FIG. 4

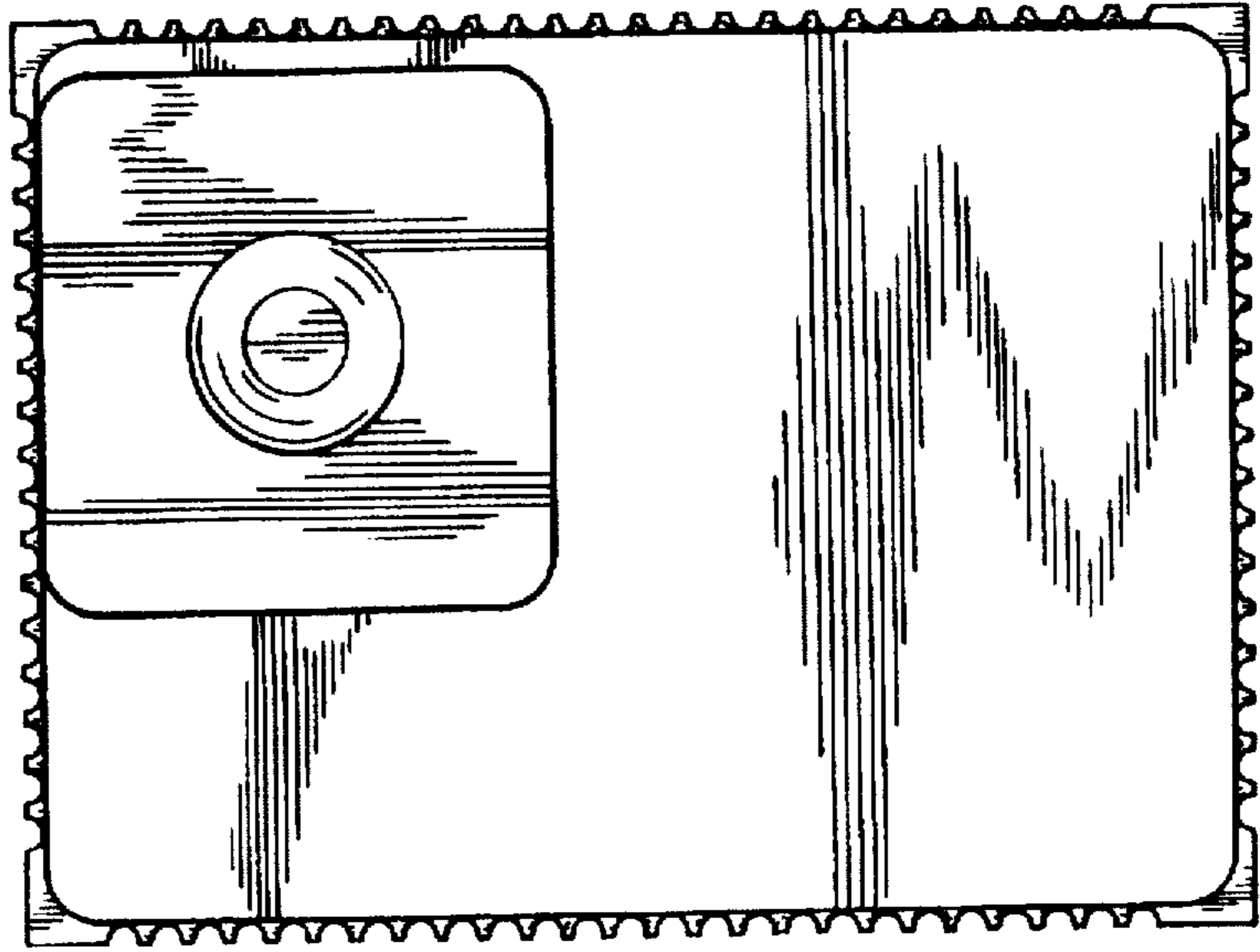


FIG. 5

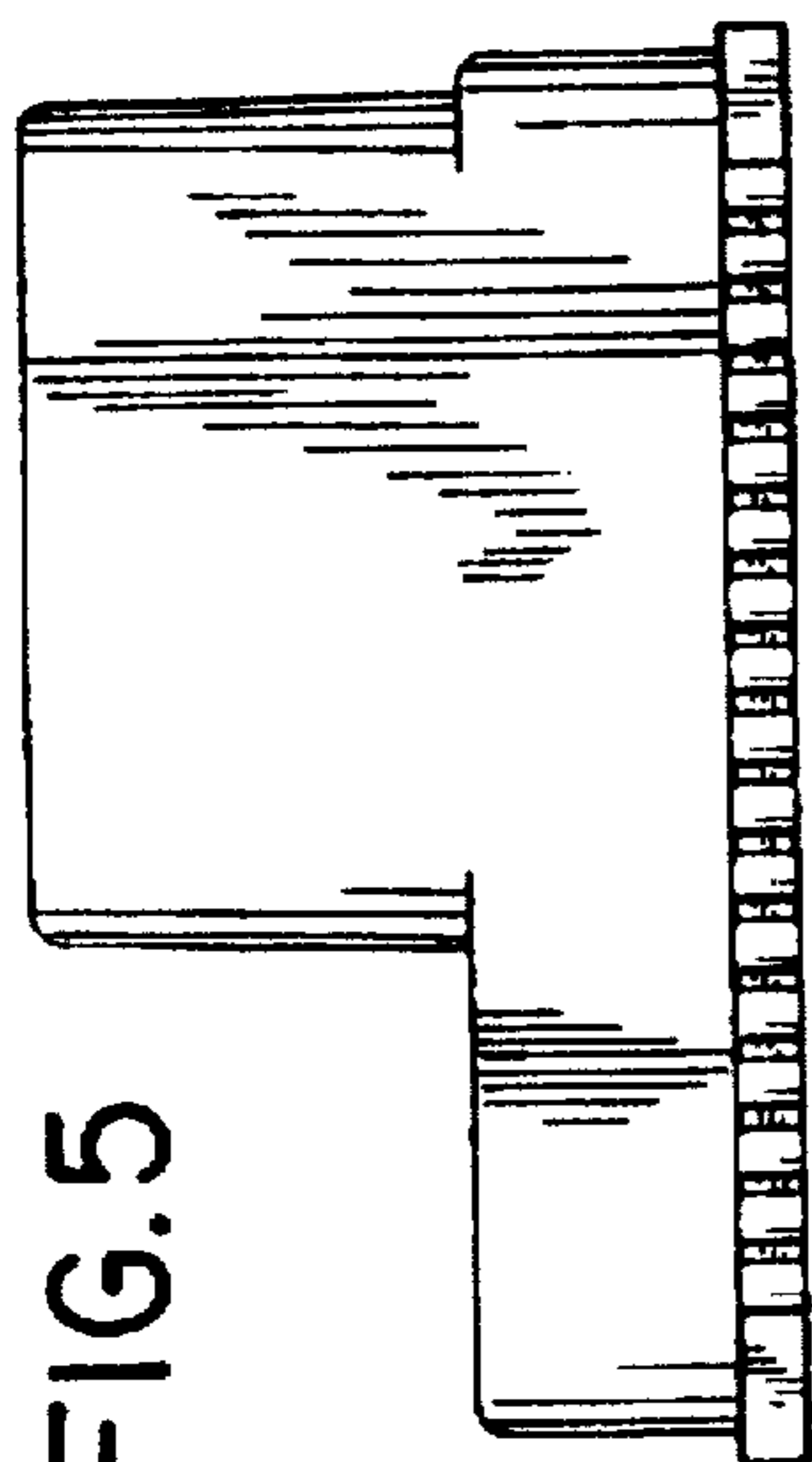


FIG. 6

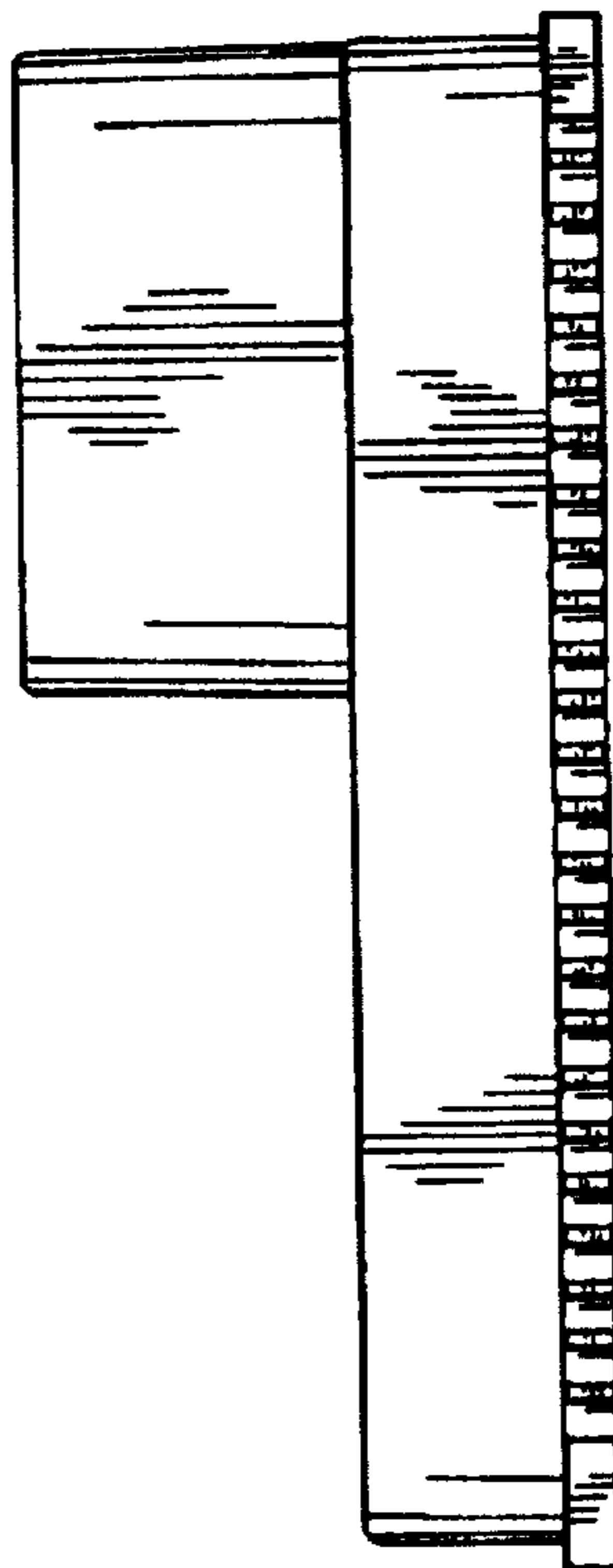


FIG. 7

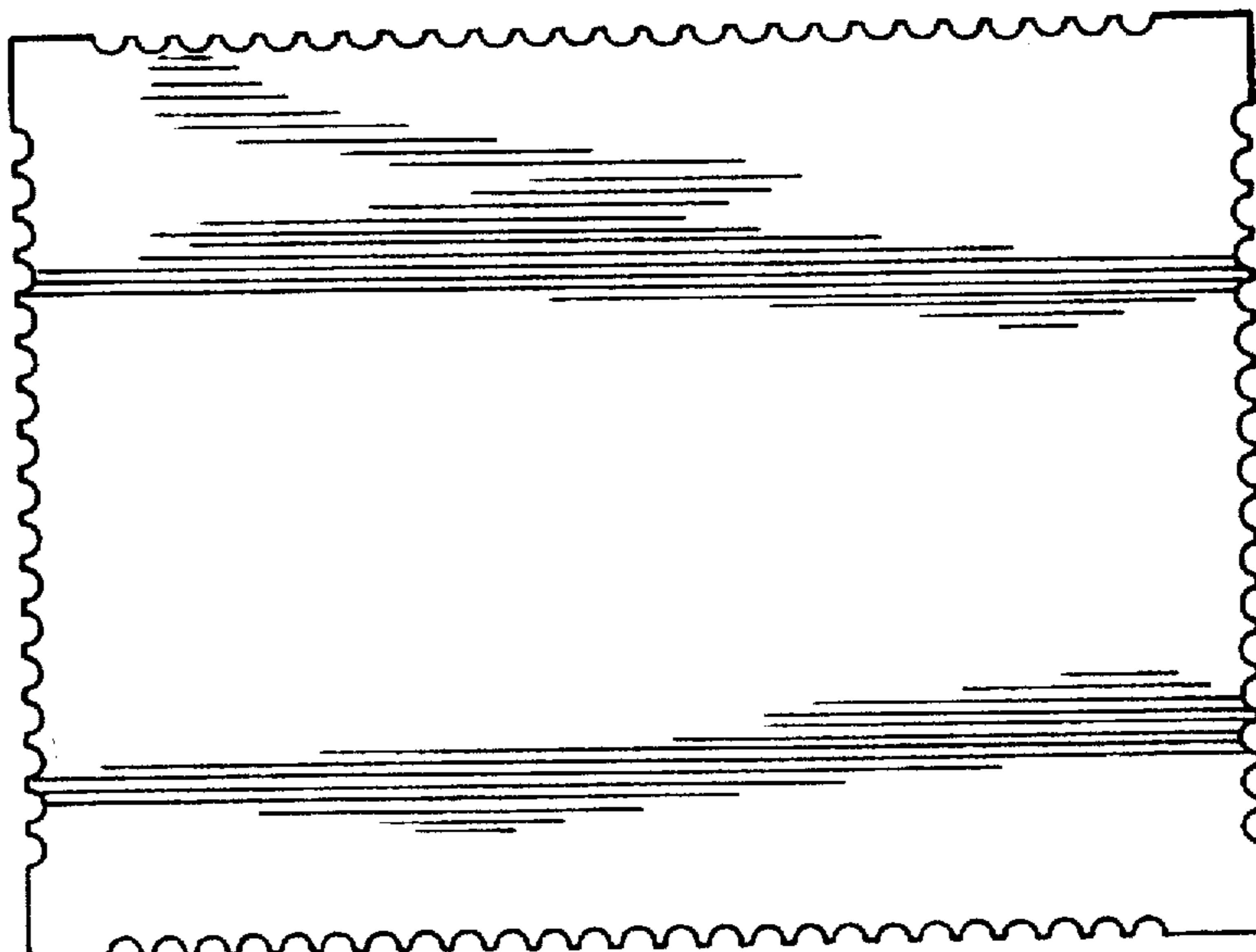


FIG. 8

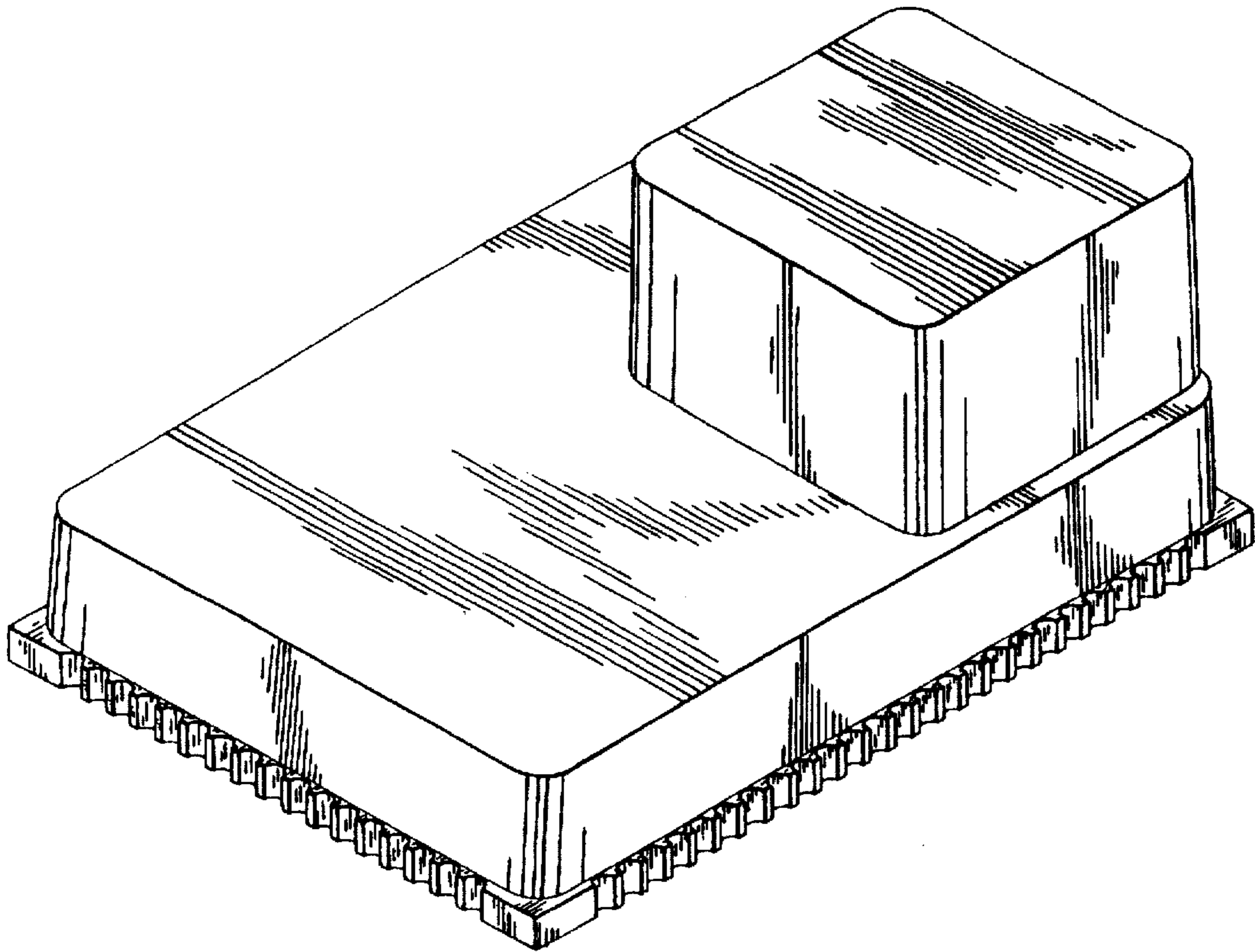


FIG. 9

